- 1. In a heat pipe in which a boundary structure forms an enclosed vapor chamber, the improvement comprising: at least one mounting hole penetrating the heat pipe.
- 2. In a heat pipe in which a boundary structure forms an enclosed vapor chamber the improvement comprising: at least one mounting hole penetrating the heat pipe, with the mounting hole isolated from the vapor chamber by being located within a sealed structure which is sealed to the boundary structure so that the mounting hole through the heat pipe has no access to the vapor chamber.
- 3. The heat pipe of claim 2 wherein the sealed structure is a column spanning the boundary structure.
- 4. The heat pipe of claim 2 wherein the sealed structure is a depression within one part of the boundary structure which contacts and is bonded to another part of the boundary structure.
- 5. The heat pipe of claim 2 wherein the sealed structure is a lip located at an edge of the boundary structure which is bonded to another lip at the edge of the boundary structure.
- 6. In a heat pipe in which a boundary structure forms an enclosed vapor chamber, with a capillary wick within the heat pipe attached to the part of the heat pipe which is in contact with a heat source, so that the capillary wick acts as the heat pipe evaporator, the improvement comprising: the capillary wick

being constructed with at least two separate sections of different materials and with a section located at the part of the heat pipe which is in contact with the heat source being formed of a material with higher heat conductivity than sections located at parts of the heat pipe not in contact with the heat source.

7. The heat pipe of claim 6 wherein the section of higher heat conductivity is constructed of sintered silver powder.

GB BB